

# SOT1190-1

plastic low profile fine-pitch ball grid array package; 144 balls,  
0.8 mm pitch, 10 mm x 10 mm x 1 mm body

11 October 2018

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LFBGA144
<b>Package type industry code</b>	LFBGA144
<b>Package style descriptive code</b>	LFBGA (low profile fine-pitch ball grid array)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-205
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	10-01-2013
<b>Manufacturer package code</b>	SOT1190

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	9.9	10	10.1	mm
package width	9.9	10	10.1	mm
seated height	1.25	1.35	1.5	mm
package height	0.95	1	1.1	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	144	-	



2 Package outline

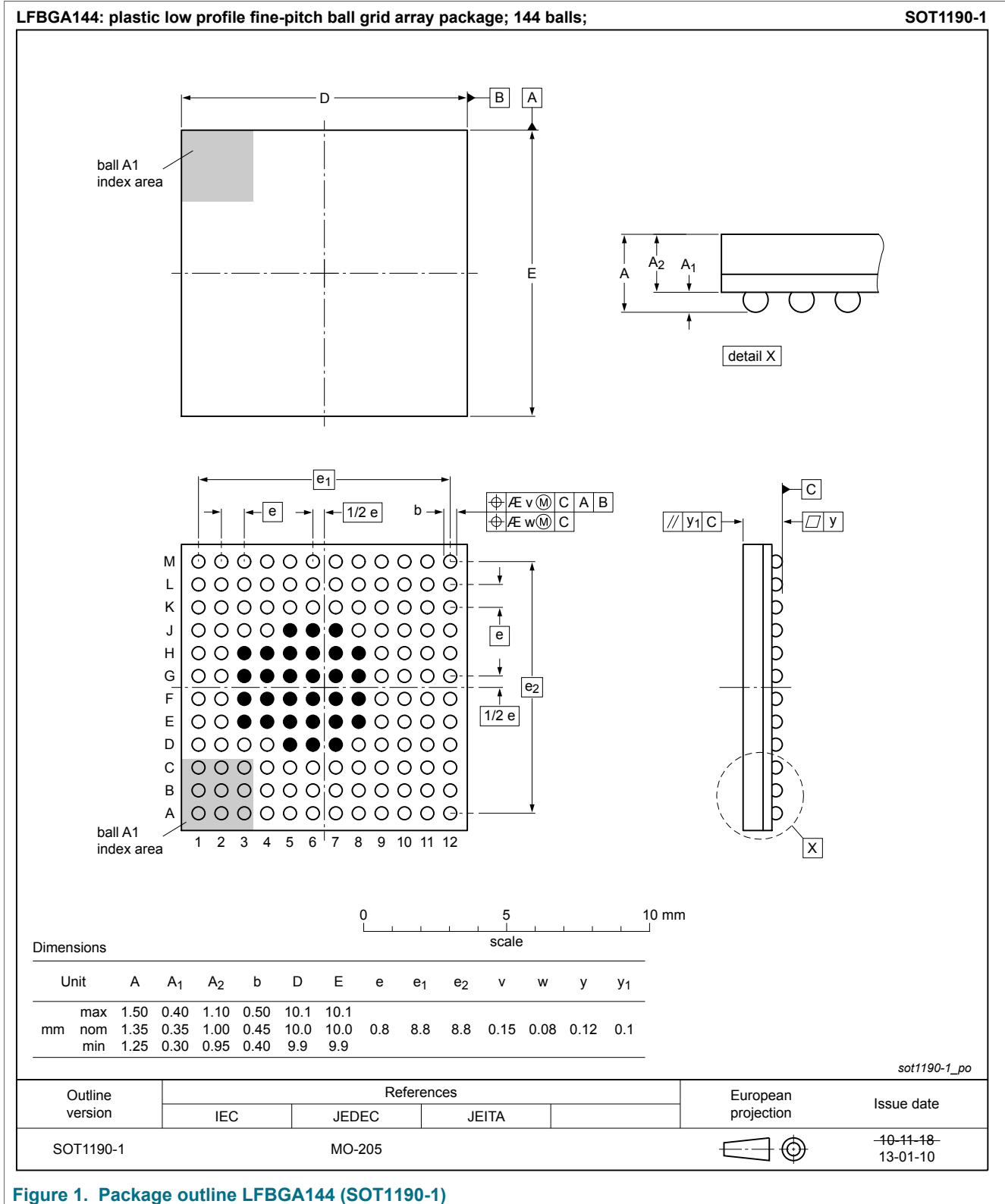


Figure 1. Package outline LFBGA144 (SOT1190-1)

### 3 Legal information

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